

IN THE SPECIFICATION

Please replace Paragraph [0025] on Page 8 with the following paragraph:

- - [0025] Illustrated in Figure 1B is the combination of the package substrate subassembly with the solder balls 36 and the jig 104 after having been flipped. As illustrated in Figure 1C the jig 104 is then removed and the solder balls remain on the bond pads 34 due to the tackiness provided by the flux on the bond pads 34. The solder balls 36 are then heated and allow to cool. The solder balls [[34A]] 36 melt when they are heated, and again solidify when they are allowed to cool, so that they attach to the bond pads 34. Because separate isolated lands are formed on, for example, the power bond pad 34A, the solder balls 36 do not reflow into one another, allowing the solder balls 36 to keep a spherical shape. By keeping the power solder balls 36A separated from one another, the solder balls can keep their spherical shape and co-planarity to other solder balls. This improves the printed board circuit assembly yields during the attachment process of the electronic package to the printed circuit board. It is believed that printed circuit assembly yields is improved because all of the solder balls 36A, 36B, and 36C are co-planar to each other and reflow in the same manner when subsequently being attached to terminals of a printed circuit board. - -